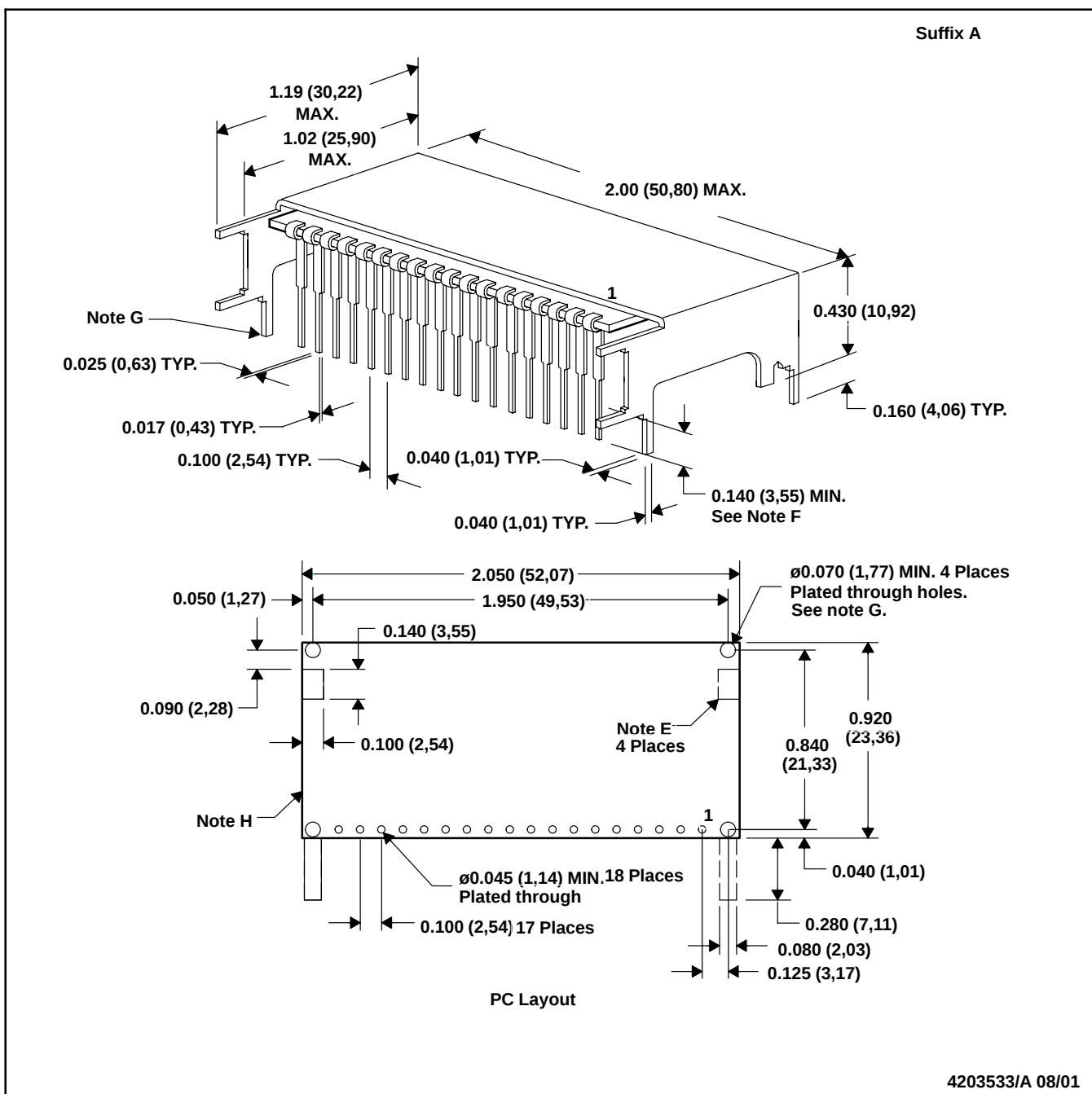


EPA (R-MSIP-T18)

METAL SINGLE-IN-LINE MODULE



NOTES: A. All linear dimensions are in inches (mm).
B. This drawing is subject to change without notice.
C. 2 place decimals are ± 0.030 (± 0.76 mm).
D. 3 place decimals are ± 0.010 (± 0.25 mm).
E. Recommended mechanical keep out area.

F. Electrical pin length mounted on printed circuit board, from seating plane to pin end.
G. The case maybe electrically connected to power ground plane.
H. Case outline reference.

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